



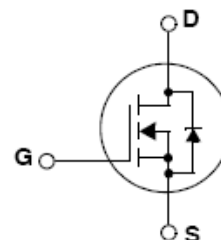
BYD Microelectronics Co., Ltd.

BF960NF06T

60V N-Channel MOSFET

General Description

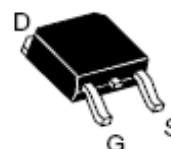
This Power MOSFET device has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any application with low gate drive requirement.



Features

- $V_{DS} = 60\text{ V}$
- $I_D = 60\text{ A}$
- Typical $R_{DS(ON)} = 10\text{ m}\Omega$ ($V_{GS} = 10\text{ V}, I_D = 30\text{ A}$)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

TO-252



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	60	V
I_D	Drain Current(continuous)at $T_c = 25^\circ\text{C}$	60	A
I_{DM}	Drain Current (pulsed) (Note1)	240	A
V_{GS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (Note2)	215	mJ
I_{AR}	Avalanche Current (Note1)	38	A
P_D	Power Dissipation ($T_c = 25^\circ\text{C}$)	138	W
T_J, T_{stg}	Operating junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose	300	$^\circ\text{C}$



Ordering Information

Part Number	Package	Packaging
BF960NF06T	TO-252	Tape & reel

Thermal Data

Symbol	Parameter	Max.	Unit
Rthj-Case	Thermal Resistance Junction-Case	0.9	°C/W
Rthj-Amb	Thermal Resistance Junction-Ambient	62	°C/W

Electrical Characteristics(T_c = 25°C)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D =250uA, V _{GS} =0V	60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V, T _c =25°C			1	uA
		V _{DS} =60V, V _{GS} =0V, T _c =125°C			10	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.2		2.5	V
R _{DS(on)}	Static Drain-Source On Resistance	V _{GS} =10V, I _D =30A		10	12	mΩ
C _{iss}	Input Capacitance	V _{DS} =25V, f=1MHz, V _{GS} =0V		4283		pF
C _{OSS}	Output Capacitance			159		pF
C _{rSS}	Reverse Transfer Capacitance			7		pF
t _{d(on)}	Turn-On Delay Time	V _{DD} =30V, I _D =30A V _{GS} =10V, R _G =4.7Ω (Note3, 4)		24		ns
t _r	Rise Time			15		ns
t _{d(off)}	Turn-Off Delay Time			94		ns
t _f	Fall Time			11		ns
Q _g	Total Gate Charge	V _{DS} =48V, I _D =12A V _{GS} =4.5V (Note3, 4)		24		nC
Q _{gs}	Gate-Source Charge			7		nC
Q _{gd}	Gate-Drain Charge			10		nC
V _{SD} (*)	Forward On Voltage	I _{SD} =25A, V _{GS} =0V			1.2	V
T _{rr}	Reverse Recovery Time	V _{DD} =40V, I _F =70A, di/dt=100A/us (Note3)		70		ns

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
 2. V_{DD} = 30V, L = 2mH, Starting T_J = 25°C
 3. Pulse Test : Pulse width ≤ 300μs, duty cycle ≤ 2%
 4. Essentially independent of operating temperature
- (*)Pulsed:Pulse duration



Typical characteristics (25°C unless noted)

Figure 1 Output Characteristics

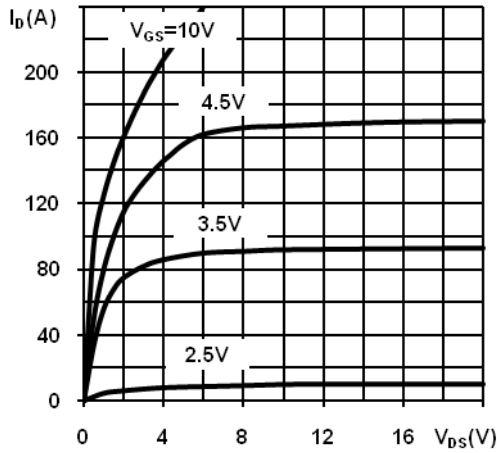


Figure 2 Transfer Characteristics

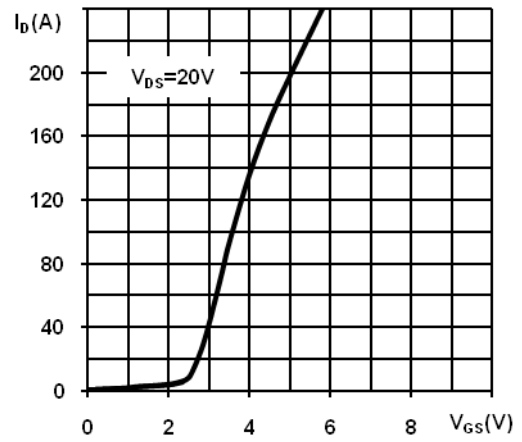


Figure 3 Normalized Threshold Voltage Vs. Temperature

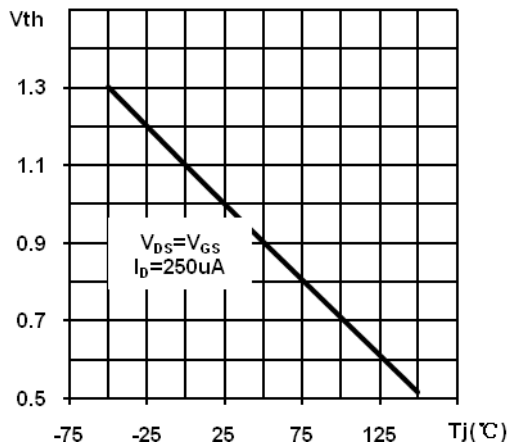


Figure 4 Normalized BV_{DSS} Vs. Temperature

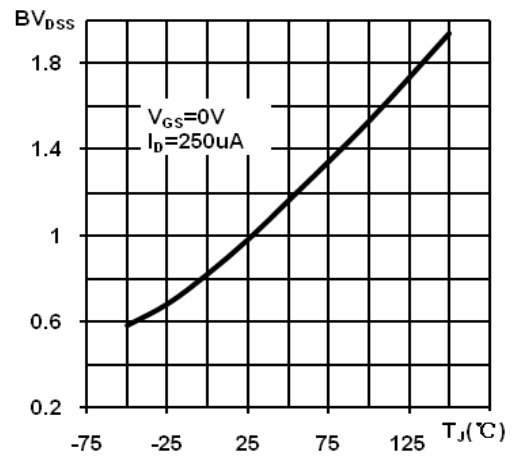


Figure 5 Normalized on Resistance Vs. Temperature

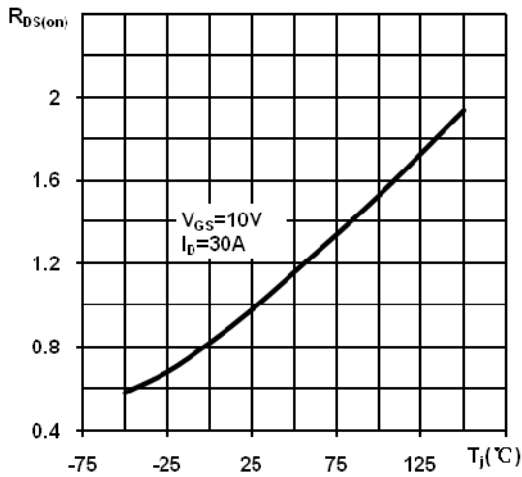


Figure 6 Source-Drain Diode Forward Characteristics

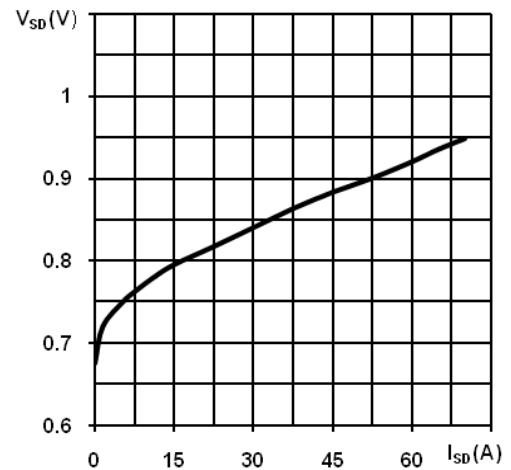


Figure 7 Capacitance

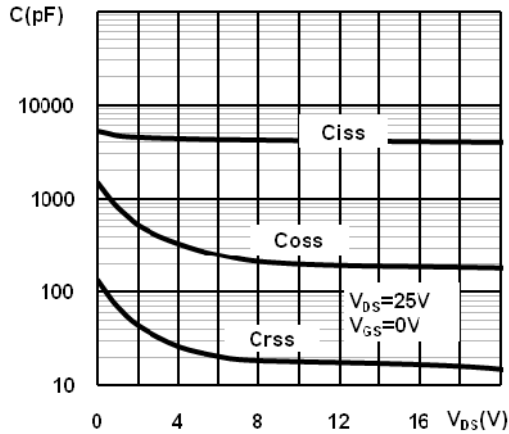


Figure 8 Gate Charge

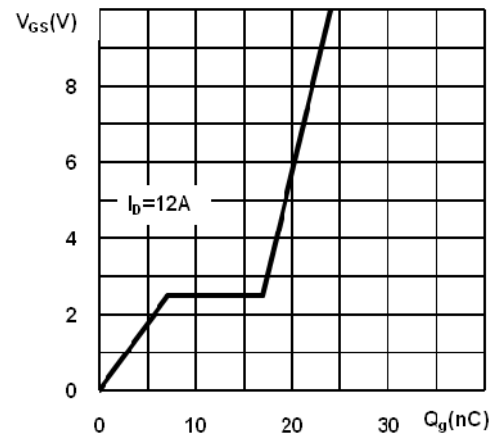


Figure 9 Safe Operating Area

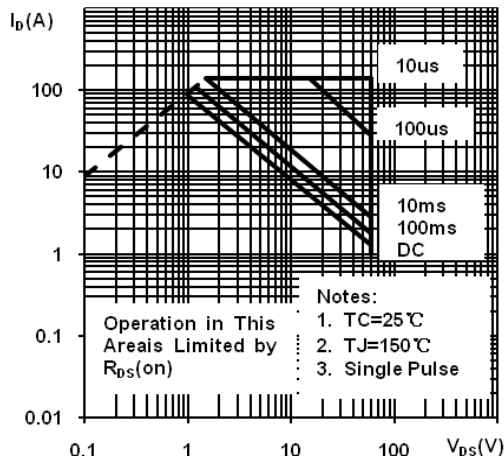


Figure 10 Maximum Drain Current Vs. Case Temperature

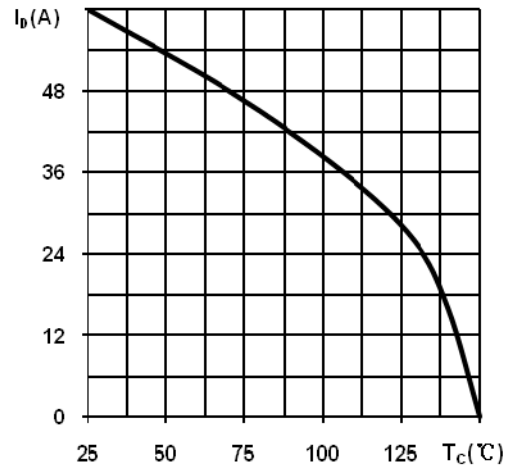
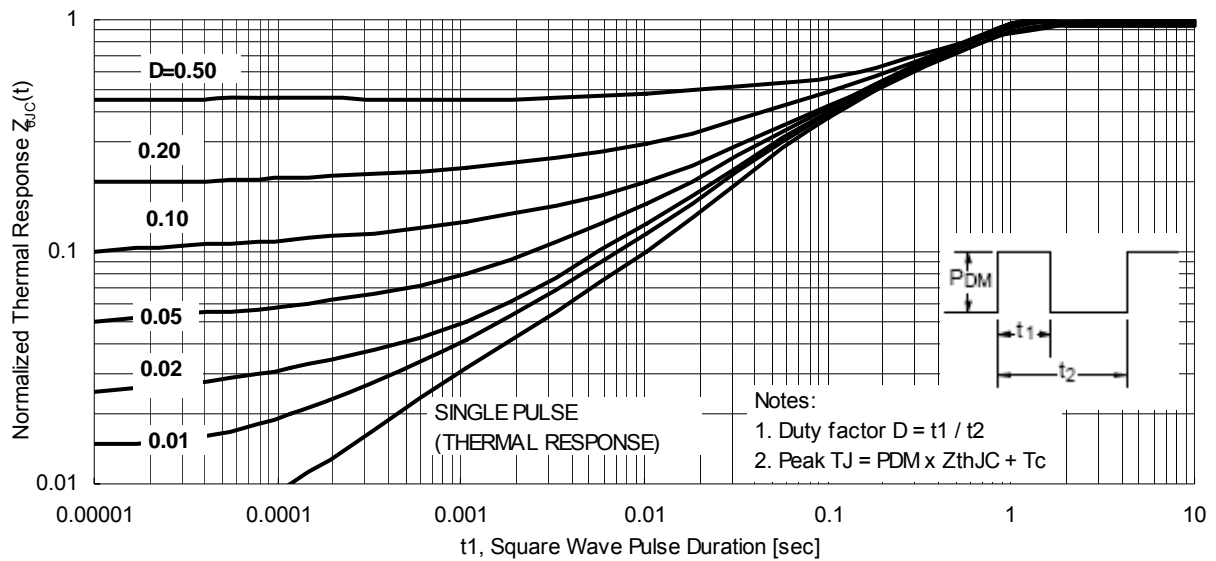
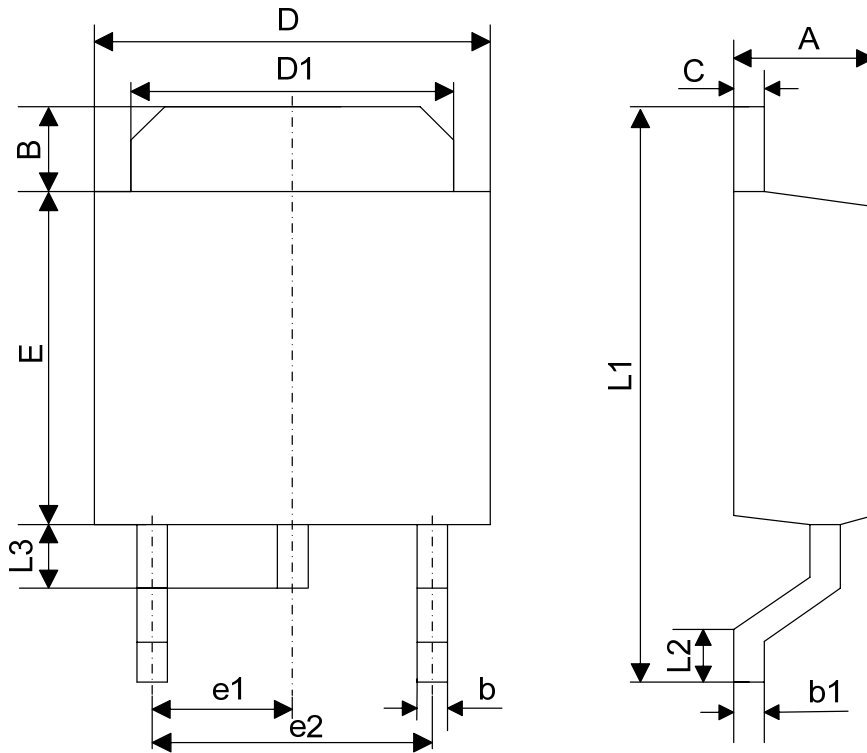


Figure 11 Normalized Maximum Transient Thermal Impedance



Package Drawing



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.2	2.4	0.087	0.094
B	1.3	1.5	0.051	0.059
b	0.55	0.65	0.022	0.026
b1	0.46	0.56	0.018	0.022
C	0.46	0.56	0.018	0.022
D	6.4	6.6	0.252	0.260
D1	5.2	5.4	0.205	0.212
E	5.4	6.15	0.212	0.242
e1	2.25	2.35	0.089	0.093
e2	4.5	4.7	0.177	0.185
L1	9.25	10.2	0.346	0.402
L2	0.95	1.45	0.037	0.057
L3	0.7	0.9	0.028	0.035



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